



General Description

- Proprietary α MOS5™ technology
- Low $R_{DS(ON)}$
- Optimized switching parameters for better EMI performance
- Enhanced body diode for robustness and fast reverse recovery

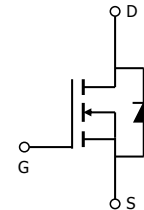
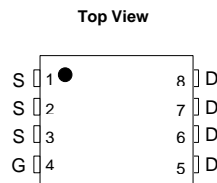
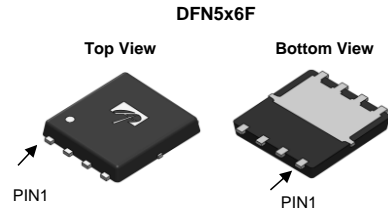
Applications

- PFC and PWM stages (Flyback, LLC) of Adapter, PC Silverbox, Server, Gaming Power Supply, Industrial, TV, Lighting

Product Summary

$V_{DS} @ T_{j,max}$	800V
I_{DM}	28A
$R_{DS(ON),max}$	< 0.85 Ω
$Q_{g,typ}$	11.5nC
$E_{oss} @ 400V$	1.4 μ J

100% UIS Tested
100% R_g Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AONS850A70	DFN5X6F	Tape&Reel	3000

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	700	V
Gate-Source Voltage	V_{GS}	± 20	V
Gate-Source Voltage (dynamic) AC($f > 1\text{Hz}$)	V_{GS}	± 30	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	7.6
		$T_C=100^\circ\text{C}$	4.8
Pulsed Drain Current ^C	I_{DM}	28	A
Continuous Drain Current	I_{DSM}	$T_A=25^\circ\text{C}$	1.5
		$T_A=70^\circ\text{C}$	1.2
Avalanche Current ^C $L=1\text{mH}$	I_{AR}	1.7	A
Repetitive avalanche energy ^C	E_{AR}	1.5	mJ
Single pulsed avalanche energy ^G	E_{AS}	11	mJ
MOSFET dv/dt ruggedness	dv/dt	100	V/ns
Peak diode recovery dv/dt		20	V/ns
Power Dissipation ^B	P_D	$T_C=25^\circ\text{C}$	113
		Derate above 25°C	0.9
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ\text{C}$	4.1
		$T_A=70^\circ\text{C}$	2.6
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10\text{s}$	$R_{\theta JA}$	25	30	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Ambient ^{A,D} Steady-State		45	55	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Case Steady-State	$R_{\theta JC}$	0.8	1.1	$^\circ\text{C}/\text{W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V, T _J =25°C	700			V
		I _D =250μA, V _{GS} =0V, T _J =150°C		800		
BV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA, V _{GS} =0V		0.61		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =700V, V _{GS} =0V			1	μA
		V _{DS} =560V, T _J =125°C			10	
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =5V, I _D =250μA	2.9	3.5	4.1	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =1.4A		0.7	0.85	Ω
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =1.4A		3		S
V _{SD}	Diode Forward Voltage	I _S =1.4A, V _{GS} =0V		0.8	1.2	V
I _S	Maximum Body-Diode Continuous Current				7.6	A
I _{SM}	Maximum Body-Diode Pulsed Current ^C				28	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		675		pF
C _{oss}	Output Capacitance			18		pF
C _{o(er)}	Effective output capacitance, energy related ^I	V _{GS} =0V, V _{DS} =0 to 480V, f=1MHz		16.5		pF
C _{o(tr)}	Effective output capacitance, time related ^J			72		pF
C _{riss}	Reverse Transfer Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		1.8		pF
R _g	Gate resistance	f=1MHz		3.1		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =480V, I _D =3.5A		11.5		nC
Q _{gs}	Gate Source Charge			4.8		nC
Q _{gd}	Gate Drain Charge			2.8		nC
T _{d(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =400V, I _D =3.5A, R _G =5Ω		18		ns
T _r	Turn-On Rise Time			9		ns
T _{d(off)}	Turn-Off DelayTime			30		ns
T _f	Turn-Off Fall Time			12		ns
T _{rr}	Body Diode Reverse Recovery Time	I _F =3.5A, dl/dt=100A/μs, V _{DS} =400V		230		ns
I _{rm}	Peak Reverse Recovery Current			16.5		A
Q _{rr}	Body Diode Reverse Recovery Charge			2.5		μC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The Power dissipation P_{DSM} is based on R_{θJA} ≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T_{J(MAX)}=150° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

G. L=60mH, I_{AS}=0.6A, R_G=25Ω, Starting T_J=25° C.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

I. C_{o(er)} is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

J. C_{o(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

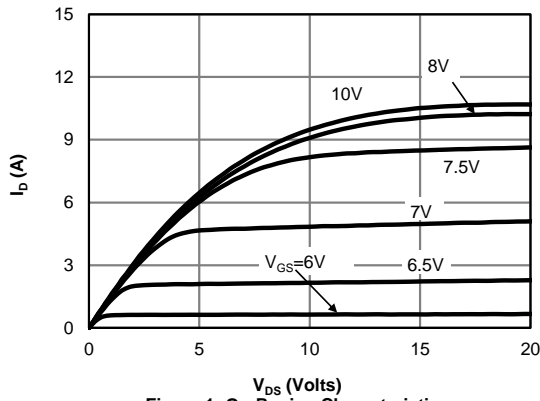


Figure 1: On-Region Characteristics

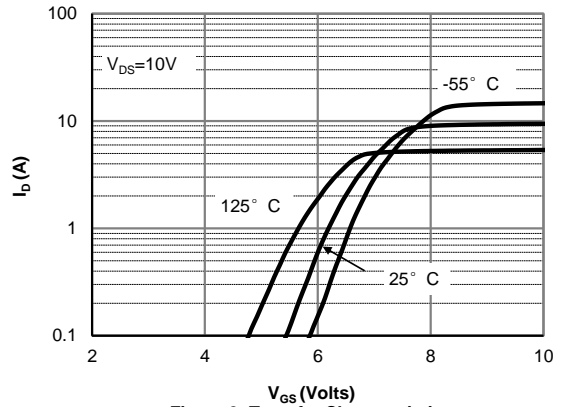


Figure 2: Transfer Characteristics

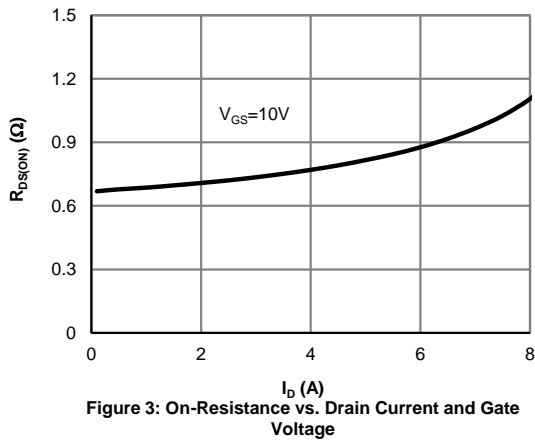


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

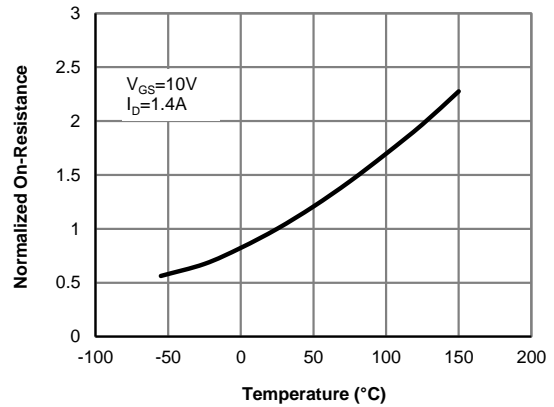


Figure 4: On-Resistance vs. Junction Temperature

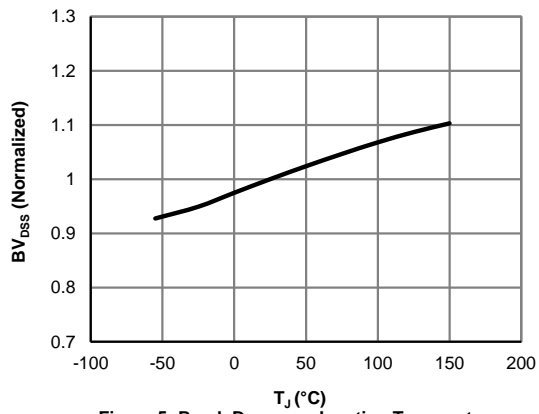


Figure 5: Break Down vs. Junction Temperature

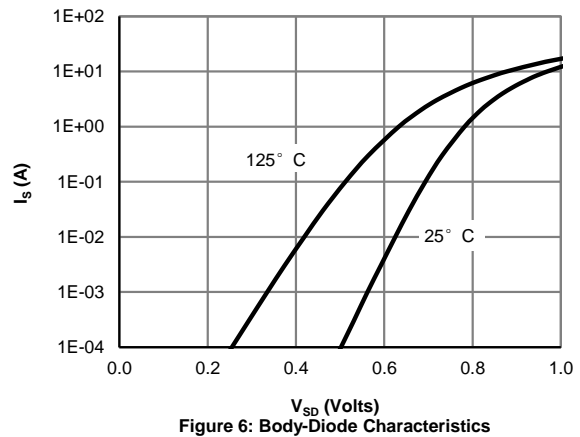


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

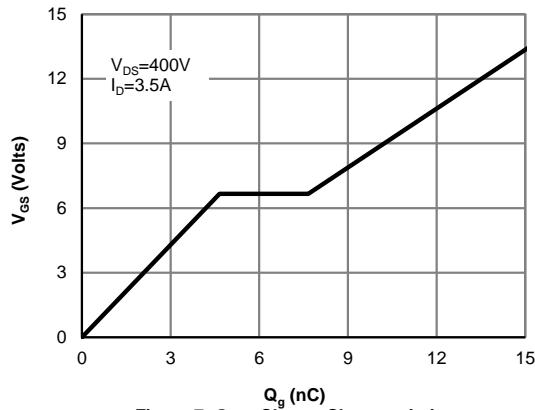


Figure 7: Gate-Charge Characteristics

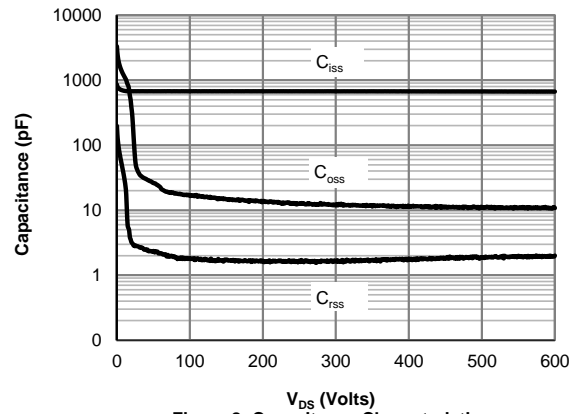


Figure 8: Capacitance Characteristics

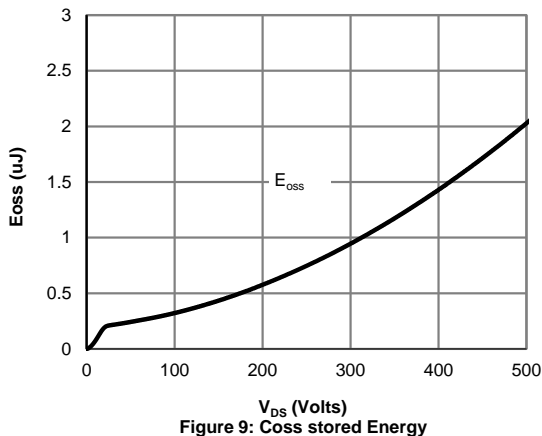


Figure 9: C_{oss} stored Energy

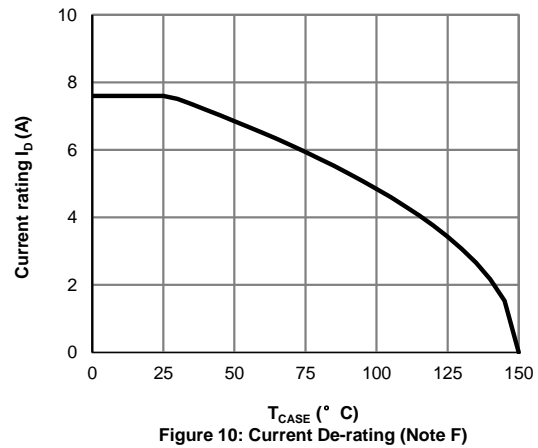


Figure 10: Current De-rating (Note F)

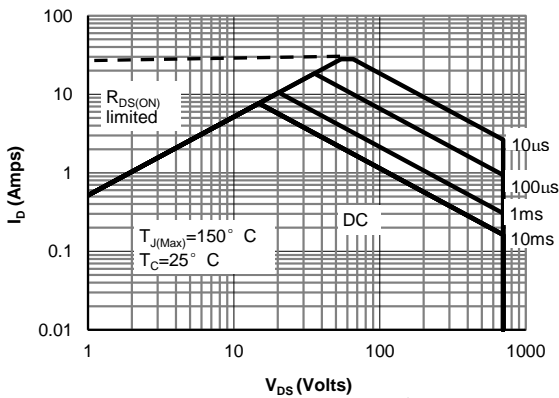


Figure 11: Maximum Forward Biased Safe Operating Area (Note F)

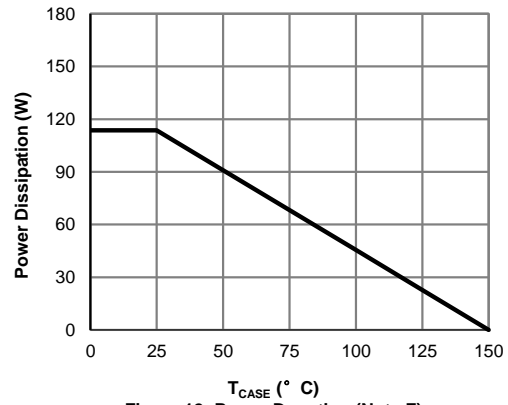


Figure 12: Power De-rating (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

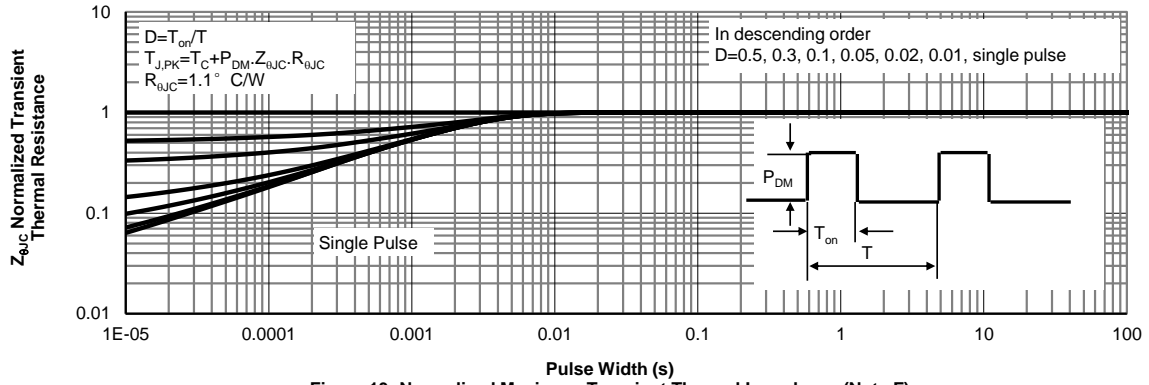


Figure 13: Normalized Maximum Transient Thermal Impedance (Note F)

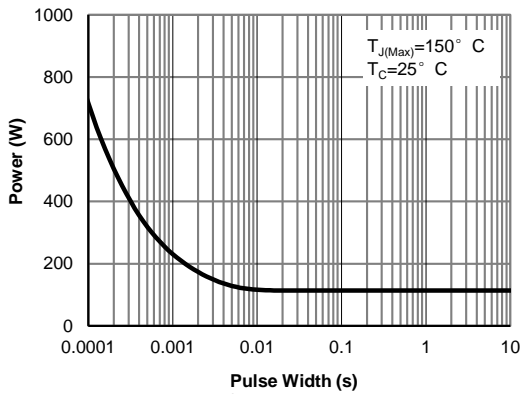


Figure 14: Single Pulse Power Rating Junction-to-Case (Note F)

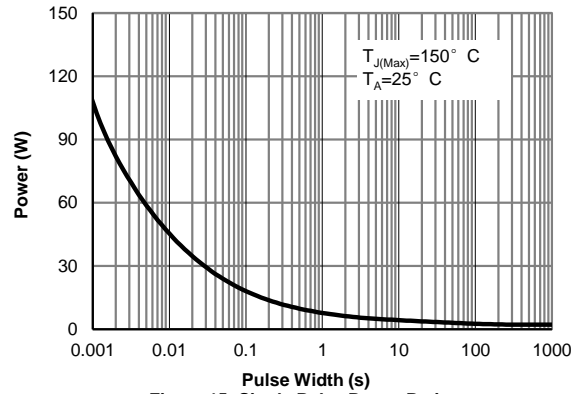


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

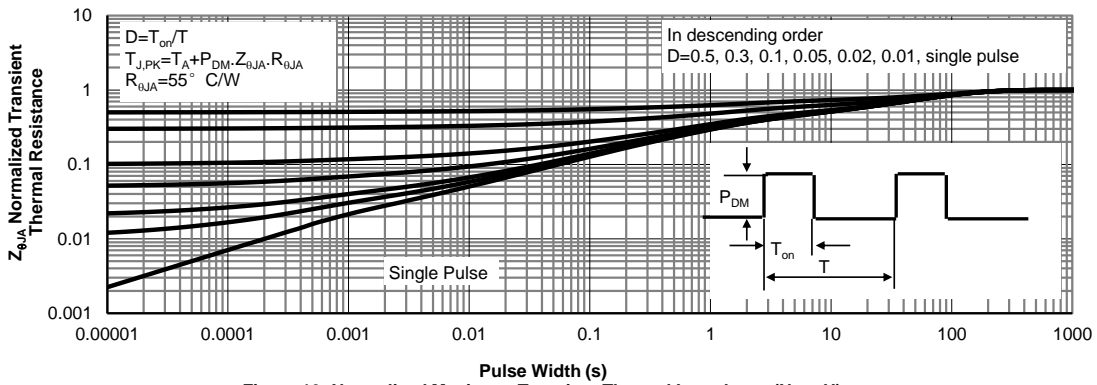
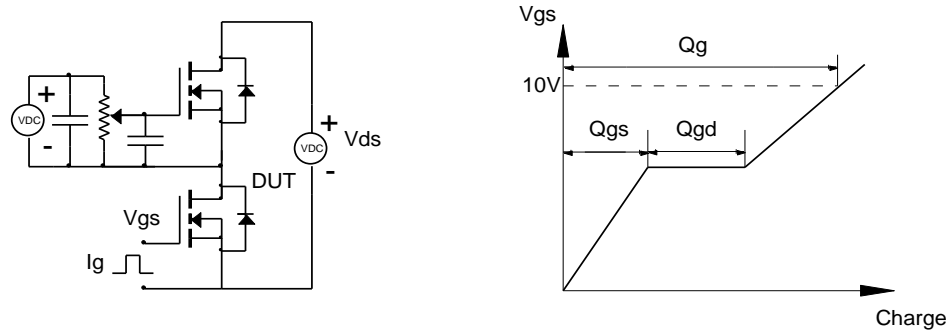
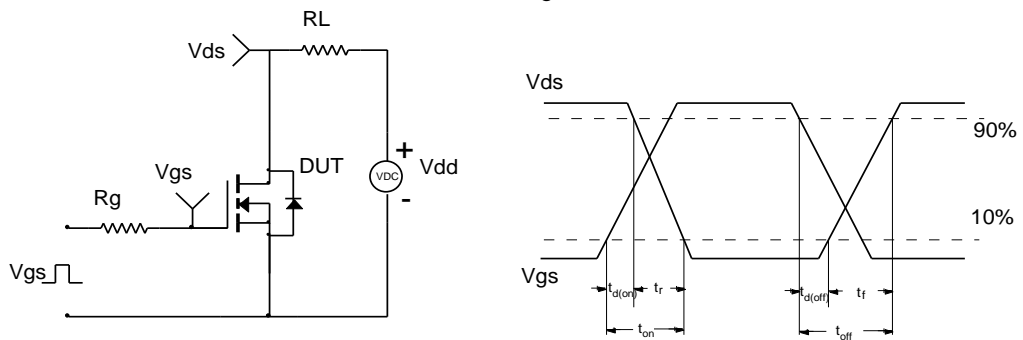


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

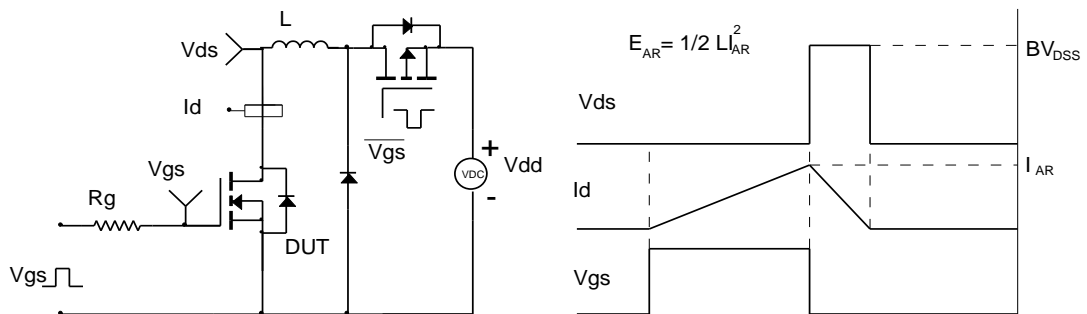
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

